



## **Adaptive Patterning for Multi-chip WLFO**

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Fan-out wafer level packaging is becoming a mainstream package format for mobile applications. Devices such as application processors and mobile chip sets are in high volume production using various fan-out package formats. However, manufacturing challenges relating to fan-out pattern alignment, reliability and cost are still prevalent with these technologies. This presentation will introduce M-Series, a fully molded fan-out wafer level package structure, and Adaptive Patterning, a method of dynamically adjusting the fan-out pattern to account for die position variability. Application of these technologies to a multi-chip package will be demonstrated.

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